



Welcome to [E-XFL.COM](#)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

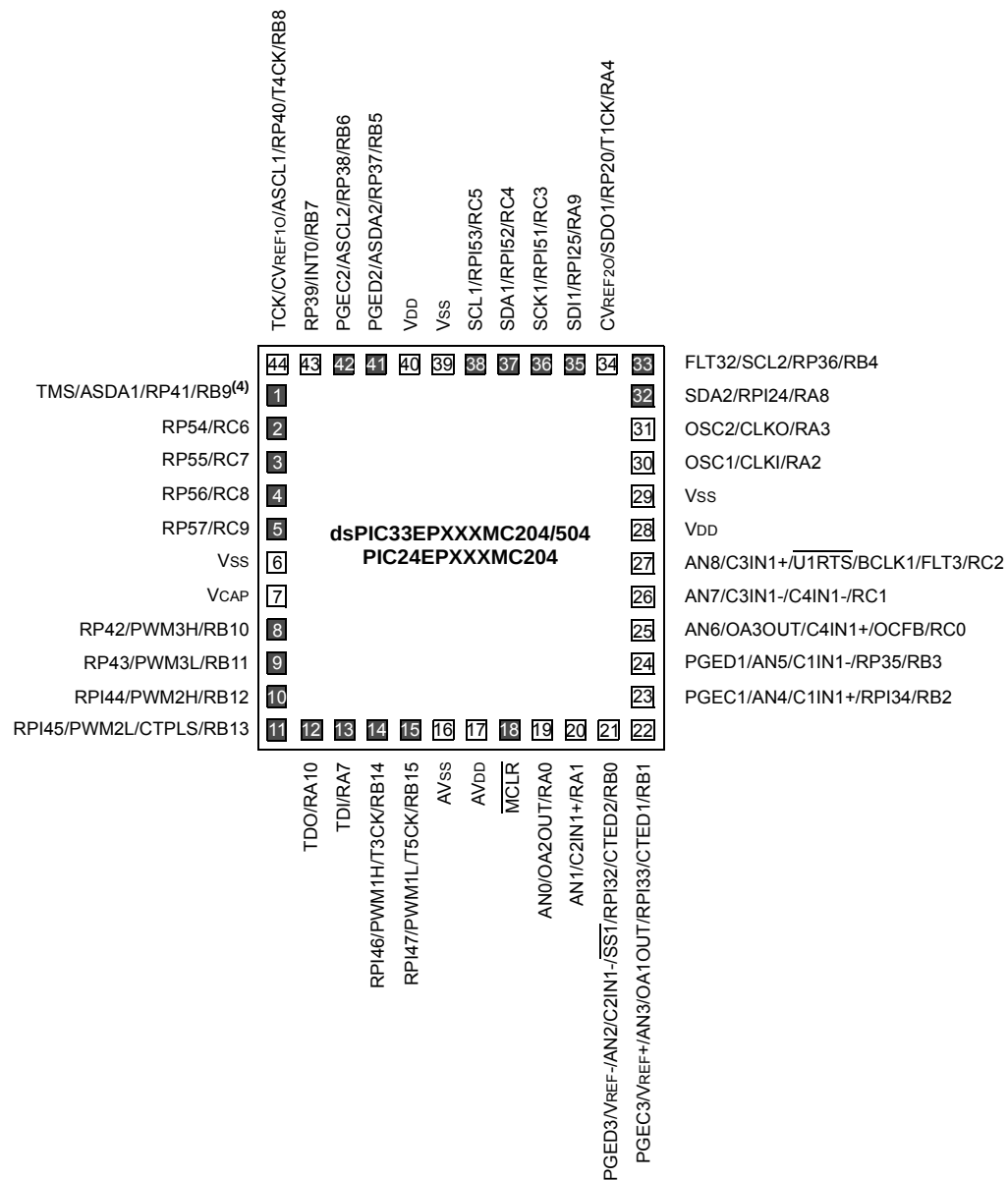
Details

Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPS
Connectivity	CANbus, I ² C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (10.7K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFTLA Exposed Pad
Supplier Device Package	44-VTLA (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep32mc504t-e-tl

Pin Diagrams (Continued)



■ = Pins are up to 5V tolerant



- Note 1:** The RPN/RPIN pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.
- 2:** Every I/O port pin (RAX-RGX) can be used as a Change Notification pin (CNAX-CNGX). See **Section 11.0 “I/O Ports”** for more information.
- 3:** The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to Vss externally.
- 4:** There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

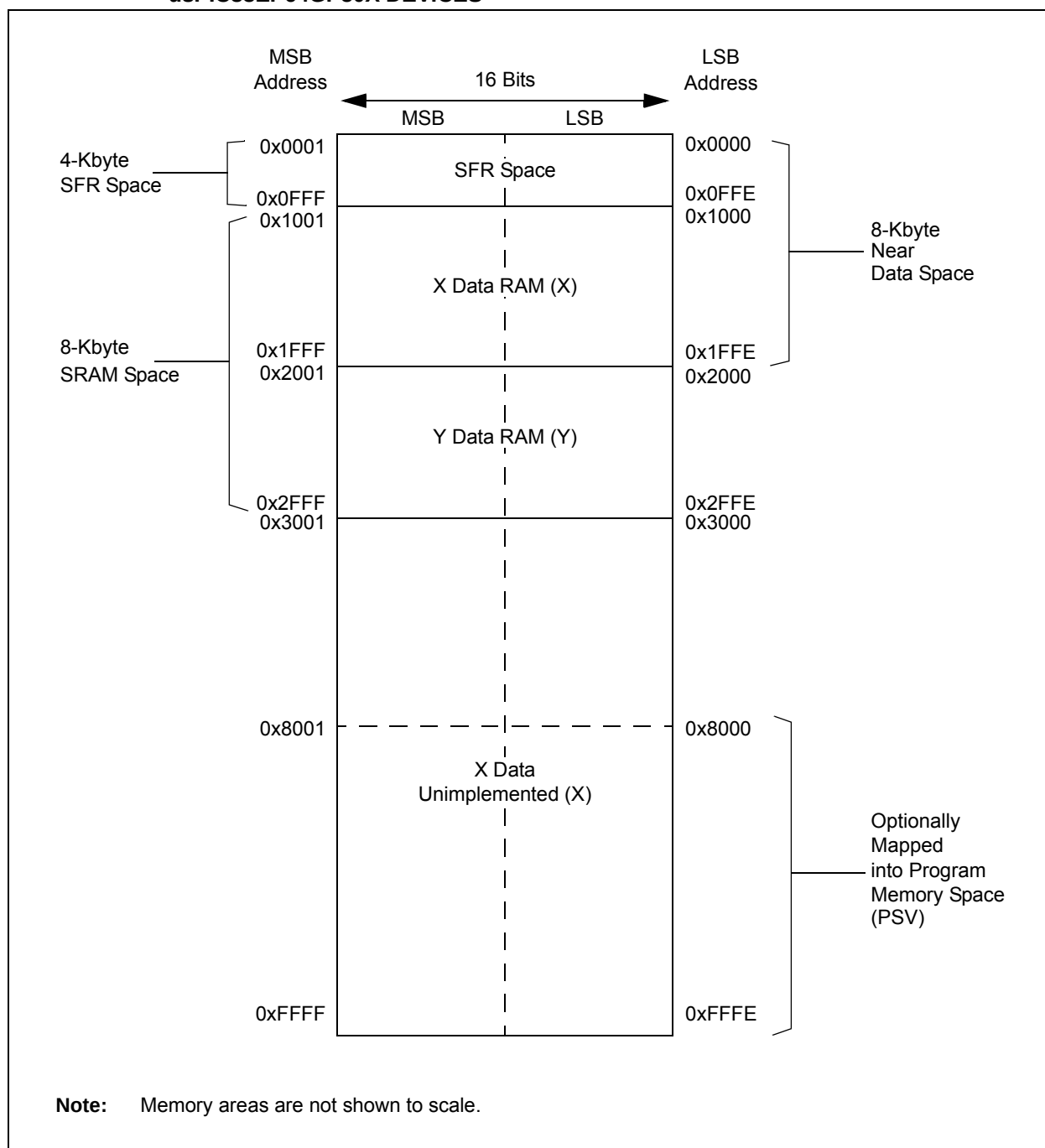
FIGURE 4-8: DATA MEMORY MAP FOR dsPIC33EP64MC20X/50X AND dsPIC33EP64GP50X DEVICES

TABLE 4-12: PWM REGISTER MAP FOR dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PTCON	0C00	PTEN	—	PTSIDL	SESTAT	SEIEN	EIPU	SYNCPOL	SYNCOEN	SYNCEN	SYNCSRC<2:0>			SEVTPS<3:0>				0000
PTCON2	0C02	—	—	—	—	—	—	—	—	—	—	—	—	—	PCLKDIV<2:0>			0000
PTPER	0C04	PTPER<15:0>																00F8
SEVTCMP	0C06	SEVTCMP<15:0>																0000
MDC	0C0A	MDC<15:0>																0000
CHOP	0C1A	CHPCLKEN	—	—	—	—	—	CHOPCLK<9:0>										0000
PWMKEY	0C1E	PWMKEY<15:0>																0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-13: PWM GENERATOR 1 REGISTER MAP FOR dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets	
PWMCON1	0C20	FLTSTAT	CLSTAT	TRGSTAT	FLTIEEN	CLIEEN	TRGIEEN	ITB	MDCS	DTC<1:0>		DTCP	—	MTBS	CAM	XPRES	IUE	0000	
IOCON1	0C22	PENH	PENL	POLH	POLL	PMOD<1:0>		OVRENH	OVRENL	OVRDAT<1:0>		FLTDAT<1:0>		CLDAT<1:0>		SWAP	OSYNC	C000	
FCLCON1	0C24	—	CLSRC<4:0>					CLPOL	CLMOD	FLTSRC<4:0>					FLTPOL	FLTMOD<1:0>		0000	
PDC1	0C26	PDC1<15:0>																	FFF8
PHASE1	0C28	PHASE1<15:0>																	0000
DTR1	0C2A	—	—	DTR1<13:0>														0000	
ALTDTR1	0C2C	—	—	ALTDTR1<13:0>														0000	
TRIG1	0C32	TRGCMPL<15:0>																	0000
TRGCON1	0C34	TRGDIV<3:0>				—	—	—	—	—	—	TRGSTRT<5:0>							0000
LEBCON1	0C3A	PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—	—	—	BCH	BCL	BPHH	BPHL	BPLH	BPLL	0000	
LEBDLY1	0C3C	—	—	—	—	LEB<11:0>												0000	
AUXCON1	0C3E	—	—	—	—	BLANKSEL<3:0>				—	—	CHOPSEL<3:0>				CHOPHEN	CHOPLEN	0000	

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-21: ECAN1 REGISTER MAP WHEN WIN (C1CTRL1<0>) = 0 OR 1 FOR dsPIC33EPXXXMC/GP50X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
C1CTRL1	0400	—	—	CSIDL	ABAT	CANCKS	REQOP<2:0>			OPMODE<2:0>			—	CANCAP	—	—	WIN	0480
C1CTRL2	0402	—	—	—	—	—	—	—	—	—	—	—	DNCNT<4:0>					0000
C1VEC	0404	—	—	—	FILHIT<4:0>					—	ICODE<6:0>							0040
C1FCTRL	0406	DMABS<2:0>			—	—	—	—	—	—	—	—	FSA<4:0>					0000
C1FIFO	0408	—	—	FBP<5:0>						—	—	FNRB<5:0>						0000
C1INTF	040A	—	—	TXBO	TXBP	RXBP	TXWAR	RXWAR	EWARN	IVRIF	WAKIF	ERRIF	—	FIFOIF	RBOVIF	RBIF	TBIF	0000
C1INTE	040C	—	—	—	—	—	—	—	—	IVRIE	WAKIE	ERRIE	—	FIFOIE	RBOVIE	RBIE	TBIE	0000
C1EC	040E	TERRCNT<7:0>								RERRCNT<7:0>								0000
C1CFG1	0410	—	—	—	—	—	—	—	—	SJW<1:0>		BRP<5:0>						0000
C1CFG2	0412	—	WAKFIL	—	—	—	SEG2PH<2:0>			SEG2PHTS	SAM	SEG1PH<2:0>			PRSEG<2:0>			0000
C1FEN1	0414	FLTEN15	FLTEN14	FLTEN13	FLTEN12	FLTEN11	FLTEN10	FLTEN9	FLTEN8	FLTEN7	FLTEN6	FLTEN5	FLTEN4	FLTEN3	FLTEN2	FLTEN1	FLTEN0	FFFF
C1FMSKSEL1	0418	F7MSK<1:0>		F6MSK<1:0>		F5MSK<1:0>		F4MSK<1:0>		F3MSK<1:0>		F2MSK<1:0>		F1MSK<1:0>		F0MSK<1:0>		0000
C1FMSKSEL2	041A	F15MSK<1:0>		F14MSK<1:0>		F13MSK<1:0>		F12MSK<1:0>		F11MSK<1:0>		F10MSK<1:0>		F9MSK<1:0>		F8MSK<1:0>		0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-22: ECAN1 REGISTER MAP WHEN WIN (C1CTRL1<0>) = 0 FOR dsPIC33EPXXXMC/GP50X DEVICES ONLY

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
	0400-041E	See definition when WIN = x																
C1RXFUL1	0420	RXFUL15	RXFUL14	RXFUL13	RXFUL12	RXFUL11	RXFUL10	RXFUL9	RXFUL8	RXFUL7	RXFUL6	RXFUL5	RXFUL4	RXFUL3	RXFUL2	RXFUL1	RXFUL0	0000
C1RXFUL2	0422	RXFUL31	RXFUL30	RXFUL29	RXFUL28	RXFUL27	RXFUL26	RXFUL25	RXFUL24	RXFUL23	RXFUL22	RXFUL21	RXFUL20	RXFUL19	RXFUL18	RXFUL17	RXFUL16	0000
C1RXOVF1	0428	RXOVF15	RXOVF14	RXOVF13	RXOVF12	RXOVF11	RXOVF10	RXOVF9	RXOVF8	RXOVF7	RXOVF6	RXOVF5	RXOVF4	RXOVF3	RXOVF2	RXOVF1	RXOVF0	0000
C1RXOVF2	042A	RXOVF31	RXOVF30	RXOVF29	RXOVF28	RXOVF27	RXOVF26	RXOVF25	RXOVF24	RXOVF23	RXOVF22	RXOVF21	RXOVF20	RXOVF19	RXOVF18	RXOVF17	RXOVF16	0000
C1TR01CON	0430	TXEN1	TXABT1	TXLARB1	TXERR1	TXREQ1	RTREN1	TX1PRI<1:0>		TXEN0	TXABAT0	TXLARB0	TXERR0	TXREQ0	RTREN0	TX0PRI<1:0>		0000
C1TR23CON	0432	TXEN3	TXABT3	TXLARB3	TXERR3	TXREQ3	RTREN3	TX3PRI<1:0>		TXEN2	TXABAT2	TXLARB2	TXERR2	TXREQ2	RTREN2	TX2PRI<1:0>		0000
C1TR45CON	0434	TXEN5	TXABT5	TXLARB5	TXERR5	TXREQ5	RTREN5	TX5PRI<1:0>		TXEN4	TXABAT4	TXLARB4	TXERR4	TXREQ4	RTREN4	TX4PRI<1:0>		0000
C1TR67CON	0436	TXEN7	TXABT7	TXLARB7	TXERR7	TXREQ7	RTREN7	TX7PRI<1:0>		TXEN6	TXABAT6	TXLARB6	TXERR6	TXREQ6	RTREN6	TX6PRI<1:0>		xxxx
C1RXD	0440	ECAN1 Receive Data Word																xxxx
C1TXD	0442	ECAN1 Transmit Data Word																xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 16-15: FCLCONx: PWMx FAULT CURRENT-LIMIT CONTROL REGISTER⁽¹⁾

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	CLSRC4	CLSRC3	CLSRC2	CLSRC1	CLSRC0	CLPOL ⁽²⁾	CLMOD
bit 15							bit 8

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0
FLTSRC4	FLTSRC3	FLTSRC2	FLTSRC1	FLTSRC0	FLTPOL ⁽²⁾	FLTMOD1	FLTMOD0
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-10 **CLSRC<4:0>:** Current-Limit Control Signal Source Select for PWM Generator # bits

11111 = Fault 32

11110 = Reserved

.

.

.

01100 = Reserved

01011 = Comparator 4

01010 = Op Amp/Comparator 3

01001 = Op Amp/Comparator 2

01000 = Op Amp/Comparator 1

00111 = Reserved

00110 = Reserved

00101 = Reserved

00100 = Reserved

00011 = Fault 4

00010 = Fault 3

00001 = Fault 2

00000 = Fault 1 (**default**)

bit 9 **CLPOL:** Current-Limit Polarity for PWM Generator # bit⁽²⁾

1 = The selected current-limit source is active-low

0 = The selected current-limit source is active-high

bit 8 **CLMOD:** Current-Limit Mode Enable for PWM Generator # bit

1 = Current-Limit mode is enabled

0 = Current-Limit mode is disabled

Note 1: If the PWMLOCK Configuration bit (FOSCSEL<6>) is a '1', the IOCONx register can only be written after the unlock sequence has been executed.

2: These bits should be changed only when PTEN = 0. Changing the clock selection during operation will yield unpredictable results.

REGISTER 16-16: LEBCONx: PWMx LEADING-EDGE BLANKING CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—
bit 15						bit 8	
U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	BCH ⁽¹⁾	BCL ⁽¹⁾	BPHH	BPHL	BPLH	BPLL
bit 7						bit 0	

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 15 **PHR:** PWMxH Rising Edge Trigger Enable bit
1 = Rising edge of PWMxH will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores rising edge of PWMxH
- bit 14 **PHF:** PWMxH Falling Edge Trigger Enable bit
1 = Falling edge of PWMxH will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores falling edge of PWMxH
- bit 13 **PLR:** PWMxL Rising Edge Trigger Enable bit
1 = Rising edge of PWMxL will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores rising edge of PWMxL
- bit 12 **PLF:** PWMxL Falling Edge Trigger Enable bit
1 = Falling edge of PWMxL will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores falling edge of PWMxL
- bit 11 **FLTLEBEN:** Fault Input Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to selected Fault input
0 = Leading-Edge Blanking is not applied to selected Fault input
- bit 10 **CLLEBEN:** Current-Limit Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to selected current-limit input
0 = Leading-Edge Blanking is not applied to selected current-limit input
- bit 9-6 **Unimplemented:** Read as '0'
- bit 5 **BCH:** Blanking in Selected Blanking Signal High Enable bit⁽¹⁾
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is high
0 = No blanking when selected blanking signal is high
- bit 4 **BCL:** Blanking in Selected Blanking Signal Low Enable bit⁽¹⁾
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is low
0 = No blanking when selected blanking signal is low
- bit 3 **BPHH:** Blanking in PWMxH High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is high
0 = No blanking when PWMxH output is high
- bit 2 **BPHL:** Blanking in PWMxH Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is low
0 = No blanking when PWMxH output is low
- bit 1 **BPLH:** Blanking in PWMxL High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is high
0 = No blanking when PWMxL output is high
- bit 0 **BPLL:** Blanking in PWMxL Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is low
0 = No blanking when PWMxL output is low

Note 1: The blanking signal is selected via the BLANKSELx bits in the AUXCONx register.

18.1 SPI Helpful Tips

1. In Frame mode, if there is a possibility that the master may not be initialized before the slave:
 - a) If FRMPOL (SPIxCON2<13>) = 1, use a pull-down resistor on $\overline{SSx}$.
 - b) If FRMPOL = 0, use a pull-up resistor on $\overline{SSx}$.

Note: This insures that the first frame transmission after initialization is not shifted or corrupted.

2. In Non-Framed 3-Wire mode, (i.e., not using $\overline{SSx}$ from a master):
 - a) If CKP (SPIxCON1<6>) = 1, always place a pull-up resistor on $\overline{SSx}$.
 - b) If CKP = 0, always place a pull-down resistor on $\overline{SSx}$.

Note: This will insure that during power-up and initialization the master/slave will not lose Sync due to an errant SCKx transition that would cause the slave to accumulate data shift errors for both transmit and receive appearing as corrupted data.

3. FRMEN (SPIxCON2<15>) = 1 and SSEN (SPIxCON1<7>) = 1 are exclusive and invalid. In Frame mode, SCKx is continuous and the Frame Sync pulse is active on the $\overline{SSx}$ pin, which indicates the start of a data frame.

Note: Not all third-party devices support Frame mode timing. Refer to the SPIx specifications in **Section 30.0 "Electrical Characteristics"** for details.

4. In Master mode only, set the SMP bit (SPIxCON1<9>) to a '1' for the fastest SPIx data rate possible. The SMP bit can only be set at the same time or after the MSTEN bit (SPIxCON1<5>) is set.

To avoid invalid slave read data to the master, the user's master software must ensure enough time for slave software to fill its write buffer before the user application initiates a master write/read cycle. It is always advisable to preload the SPIxBUF Transmit register in advance of the next master transaction cycle. SPIxBUF is transferred to the SPIx Shift register and is empty once the data transmission begins.

18.2 SPI Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
<http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464>

18.2.1 KEY RESOURCES

- **"Serial Peripheral Interface (SPI)"** (DS70569) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 21-11: CxFEN1: ECANx ACCEPTANCE FILTER ENABLE REGISTER 1

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
FLTEN15	FLTEN14	FLTEN13	FLTEN12	FLTEN11	FLTEN10	FLTEN9	FLTEN8
bit 15							bit 8

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
FLTEN7	FLTEN6	FLTEN5	FLTEN4	FLTEN3	FLTEN2	FLTEN1	FLTEN0
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-0 **FLTEN<15:0>**: Enable Filter n to Accept Messages bits
1 = Enables Filter n
0 = Disables Filter n

REGISTER 21-12: CxBUFNT1: ECANx FILTER 0-3 BUFFER POINTER REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F3BP<3:0>				F2BP<3:0>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F1BP<3:0>				F0BP<3:0>			
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-12 **F3BP<3:0>**: RX Buffer Mask for Filter 3 bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
.
.
.
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0

bit 11-8 **F2BP<3:0>**: RX Buffer Mask for Filter 2 bits (same values as bits<15:12>)

bit 7-4 **F1BP<3:0>**: RX Buffer Mask for Filter 1 bits (same values as bits<15:12>)

bit 3-0 **F0BP<3:0>**: RX Buffer Mask for Filter 0 bits (same values as bits<15:12>)

BUFFER 21-7: ECAN™ MESSAGE BUFFER WORD 6

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 7							
bit 15							
bit 8							

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 6							
bit 7							
bit 0							

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-8 **Byte 7<15:8>:** ECAN Message Byte 7 bits

bit 7-0 **Byte 6<7:0>:** ECAN Message Byte 6 bits

BUFFER 21-8: ECAN™ MESSAGE BUFFER WORD 7

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	FILHIT4 ⁽¹⁾	FILHIT3 ⁽¹⁾	FILHIT2 ⁽¹⁾	FILHIT1 ⁽¹⁾	FILHIT0 ⁽¹⁾
bit 15							
bit 8							

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							
bit 0							

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **FILHIT<4:0>:** Filter Hit Code bits⁽¹⁾
Encodes number of filter that resulted in writing this buffer.

bit 7-0 **Unimplemented:** Read as '0'

Note 1: Only written by module for receive buffers, unused for transmit buffers.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles ⁽²⁾	Status Flags Affected
25	DAW	DAW Wn	Wn = decimal adjust Wn	1	1	C
26	DEC	DEC f	$f = f - 1$	1	1	C,DC,N,OV,Z
		DEC f, WREG	WREG = $f - 1$	1	1	C,DC,N,OV,Z
		DEC Ws, Wd	$Wd = Ws - 1$	1	1	C,DC,N,OV,Z
27	DEC2	DEC2 f	$f = f - 2$	1	1	C,DC,N,OV,Z
		DEC2 f, WREG	WREG = $f - 2$	1	1	C,DC,N,OV,Z
		DEC2 Ws, Wd	$Wd = Ws - 2$	1	1	C,DC,N,OV,Z
28	DISI	DISI #lit14	Disable Interrupts for k instruction cycles	1	1	None
29	DIV	DIV.S Wm, Wn	Signed 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.SD Wm, Wn	Signed 32/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.U Wm, Wn	Unsigned 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.UD Wm, Wn	Unsigned 32/16-bit Integer Divide	1	18	N,Z,C,OV
30	DIVF	DIVF Wm, Wn ⁽¹⁾	Signed 16/16-bit Fractional Divide	1	18	N,Z,C,OV
31	DO	DO #lit15, Expr ⁽¹⁾	Do code to PC + Expr, lit15 + 1 times	2	2	None
		DO Wn, Expr ⁽¹⁾	Do code to PC + Expr, (Wn) + 1 times	2	2	None
32	ED	ED Wm*Wm, Acc, Wx, Wy, Wxd ⁽¹⁾	Euclidean Distance (no accumulate)	1	1	OA,OB,OAB,SA,SB,SAB
33	EDAC	EDAC Wm*Wm, Acc, Wx, Wy, Wxd ⁽¹⁾	Euclidean Distance	1	1	OA,OB,OAB,SA,SB,SAB
34	EXCH	EXCH Wns, Wnd	Swap Wns with Wnd	1	1	None
35	FBCL	FBCL Ws, Wnd	Find Bit Change from Left (MSb) Side	1	1	C
36	FF1L	FF1L Ws, Wnd	Find First One from Left (MSb) Side	1	1	C
37	FF1R	FF1R Ws, Wnd	Find First One from Right (LSb) Side	1	1	C
38	GOTO	GOTO Expr	Go to address	2	4	None
		GOTO Wn	Go to indirect	1	4	None
		GOTO.L Wn	Go to indirect (long address)	1	4	None
39	INC	INC f	$f = f + 1$	1	1	C,DC,N,OV,Z
		INC f, WREG	WREG = $f + 1$	1	1	C,DC,N,OV,Z
		INC Ws, Wd	$Wd = Ws + 1$	1	1	C,DC,N,OV,Z
40	INC2	INC2 f	$f = f + 2$	1	1	C,DC,N,OV,Z
		INC2 f, WREG	WREG = $f + 2$	1	1	C,DC,N,OV,Z
		INC2 Ws, Wd	$Wd = Ws + 2$	1	1	C,DC,N,OV,Z
41	IOR	IOR f	$f = f . \text{IOR} . \text{WREG}$	1	1	N,Z
		IOR f, WREG	WREG = $f . \text{IOR} . \text{WREG}$	1	1	N,Z
		IOR #lit10, Wn	$Wd = \text{lit10} . \text{IOR} . Wd$	1	1	N,Z
		IOR Wb, Ws, Wd	$Wd = Wb . \text{IOR} . Ws$	1	1	N,Z
		IOR Wb, #lit5, Wd	$Wd = Wb . \text{IOR} . \text{lit5}$	1	1	N,Z
42	LAC	LAC Wso, #Slit4, Acc	Load Accumulator	1	1	OA,OB,OAB,SA,SB,SAB
43	LNK	LNK #lit14	Link Frame Pointer	1	1	SFA
44	LSR	LSR f	$f = \text{Logical Right Shift } f$	1	1	C,N,OV,Z
		LSR f, WREG	WREG = Logical Right Shift f	1	1	C,N,OV,Z
		LSR Ws, Wd	$Wd = \text{Logical Right Shift } Ws$	1	1	C,N,OV,Z
		LSR Wb, Wns, Wnd	$Wnd = \text{Logical Right Shift } Wb \text{ by } Wns$	1	1	N,Z
		LSR Wb, #lit5, Wnd	$Wnd = \text{Logical Right Shift } Wb \text{ by lit5}$	1	1	N,Z
45	MAC	MAC Wm*Wn, Acc, Wx, Wxd, Wy, Wyd, AWB ⁽¹⁾	Multiply and Accumulate	1	1	OA,OB,OAB,SA,SB,SAB
		MAC Wm*Wm, Acc, Wx, Wxd, Wy, Wyd ⁽¹⁾	Square and Accumulate	1	1	OA,OB,OAB,SA,SB,SAB

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles ⁽²⁾	Status Flags Affected
53	NEG	NEG $Acc^{(1)}$	Negate Accumulator	1	1	OA,OB,OAB,SA,SB,SAB
		NEG f	$f = \bar{f} + 1$	1	1	C,DC,N,OV,Z
		NEG $f, WREG$	$WREG = \bar{f} + 1$	1	1	C,DC,N,OV,Z
		NEG Ws, Wd	$Wd = \bar{Ws} + 1$	1	1	C,DC,N,OV,Z
54	NOP	NOP	No Operation	1	1	None
		NOPR	No Operation	1	1	None
55	POP	POP f	Pop f from Top-of-Stack (TOS)	1	1	None
		POP Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
		POP.D Wnd	Pop from Top-of-Stack (TOS) to $W(nd):W(nd + 1)$	1	2	None
		POP.S	Pop Shadow Registers	1	1	All
56	PUSH	PUSH f	Push f to Top-of-Stack (TOS)	1	1	None
		PUSH Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
		PUSH.D Wns	Push $W(ns):W(ns + 1)$ to Top-of-Stack (TOS)	1	2	None
		PUSH.S	Push Shadow Registers	1	1	None
57	PWRSV	PWRSV $\#lit1$	Go into Sleep or Idle mode	1	1	WDTO,Sleep
58	RCALL	RCALL $Expr$	Relative Call	1	4	SFA
		RCALL Wn	Computed Call	1	4	SFA
59	REPEAT	REPEAT $\#lit15$	Repeat Next Instruction $lit15 + 1$ times	1	1	None
		REPEAT Wn	Repeat Next Instruction $(Wn) + 1$ times	1	1	None
60	RESET	RESET	Software device Reset	1	1	None
61	RETFIE	RETFIE	Return from interrupt	1	6 (5)	SFA
62	RETLW	RETLW $\#lit10, Wn$	Return with literal in Wn	1	6 (5)	SFA
63	RETURN	RETURN	Return from Subroutine	1	6 (5)	SFA
64	RLC	RLC f	$f = \text{Rotate Left through Carry } f$	1	1	C,N,Z
		RLC $f, WREG$	$WREG = \text{Rotate Left through Carry } f$	1	1	C,N,Z
		RLC Ws, Wd	$Wd = \text{Rotate Left through Carry } Ws$	1	1	C,N,Z
65	RLNC	RLNC f	$f = \text{Rotate Left (No Carry) } f$	1	1	N,Z
		RLNC $f, WREG$	$WREG = \text{Rotate Left (No Carry) } f$	1	1	N,Z
		RLNC Ws, Wd	$Wd = \text{Rotate Left (No Carry) } Ws$	1	1	N,Z
66	RRC	RRC f	$f = \text{Rotate Right through Carry } f$	1	1	C,N,Z
		RRC $f, WREG$	$WREG = \text{Rotate Right through Carry } f$	1	1	C,N,Z
		RRC Ws, Wd	$Wd = \text{Rotate Right through Carry } Ws$	1	1	C,N,Z
67	RRNC	RRNC f	$f = \text{Rotate Right (No Carry) } f$	1	1	N,Z
		RRNC $f, WREG$	$WREG = \text{Rotate Right (No Carry) } f$	1	1	N,Z
		RRNC Ws, Wd	$Wd = \text{Rotate Right (No Carry) } Ws$	1	1	N,Z
68	SAC	SAC $Acc, \#Slit4, Wdo^{(1)}$	Store Accumulator	1	1	None
		SAC.R $Acc, \#Slit4, Wdo^{(1)}$	Store Rounded Accumulator	1	1	None
69	SE	SE Ws, Wnd	$Wnd = \text{sign-extended } Ws$	1	1	C,N,Z
70	SETM	SETM f	$f = 0xFFFF$	1	1	None
		SETM $WREG$	$WREG = 0xFFFF$	1	1	None
		SETM Ws	$Ws = 0xFFFF$	1	1	None
71	SFTAC	SFTAC $Acc, Wn^{(1)}$	Arithmetic Shift Accumulator by (Wn)	1	1	OA,OB,OAB,SA,SB,SAB
		SFTAC $Acc, \#Slit6^{(1)}$	Arithmetic Shift Accumulator by $Slit6$	1	1	OA,OB,OAB,SA,SB,SAB

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 30-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended	
Parameter No.	Typ.	Max.	Units	Conditions
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP32GP50X, dsPIC33EP32MC20X/50X and PIC24EP32GP/MC20X				
DC60d	30	100	μA	-40°C
DC60a	35	100	μA	+25°C
DC60b	150	200	μA	+85°C
DC60c	250	500	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP64GP50X, dsPIC33EP64MC20X/50X and PIC24EP64GP/MC20X				
DC60d	25	100	μA	-40°C
DC60a	30	100	μA	+25°C
DC60b	150	350	μA	+85°C
DC60c	350	800	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP128GP50X, dsPIC33EP128MC20X/50X and PIC24EP128GP/MC20X				
DC60d	30	100	μA	-40°C
DC60a	35	100	μA	+25°C
DC60b	150	350	μA	+85°C
DC60c	550	1000	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP256GP50X, dsPIC33EP256MC20X/50X and PIC24EP256GP/MC20X				
DC60d	35	100	μA	-40°C
DC60a	40	100	μA	+25°C
DC60b	250	450	μA	+85°C
DC60c	1000	1200	μA	+125°C
Power-Down Current (IPD)⁽¹⁾ – dsPIC33EP512GP50X, dsPIC33EP512MC20X/50X and PIC24EP512GP/MC20X				
DC60d	40	100	μA	-40°C
DC60a	45	100	μA	+25°C
DC60b	350	800	μA	+85°C
DC60c	1100	1500	μA	+125°C

Note 1: IPD (Sleep) current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock is active; OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- MCLR = VDD, WDT and FSCM are disabled
- All peripheral modules are disabled (PMDx bits are all set)
- The VREGS bit (RCON<8>) = 0 (i.e., core regulator is set to standby while the device is in Sleep mode)
- The VREGSF bit (RCON<11>) = 0 (i.e., Flash regulator is set to standby while the device is in Sleep mode)
- JTAG is disabled

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DI50	I _{IL}	Input Leakage Current^(1,2) I/O Pins 5V Tolerant ⁽³⁾	-1	—	+1	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , Pin at high-impedance
DI51		I/O Pins Not 5V Tolerant ⁽³⁾	-1	—	+1	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , Pin at high-impedance, $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$
DI51a		I/O Pins Not 5V Tolerant ⁽³⁾	-1	—	+1	μA	Analog pins shared with external reference pins, $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$
DI51b		I/O Pins Not 5V Tolerant ⁽³⁾	-1	—	+1	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , Pin at high-impedance, $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$
DI51c		I/O Pins Not 5V Tolerant ⁽³⁾	-1	—	+1	μA	Analog pins shared with external reference pins, $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$
DI55		MCLR	-5	—	+5	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD}
DI56		OSC1	-5	—	+5	μA	V _{SS} ≤ V _{PIN} ≤ V _{DD} , XT and HS modes

- Note 1:** The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.
- 2:** Negative current is defined as current sourced by the pin.
- 3:** See the “Pin Diagrams” section for the 5V tolerant I/O pins.
- 4:** V_{IL} source < (V_{SS} – 0.3). Characterized but not tested.
- 5:** Non-5V tolerant pins V_{IH} source > (V_{DD} + 0.3), 5V tolerant pins V_{IH} source > 5.5V. Characterized but not tested.
- 6:** Digital 5V tolerant pins cannot tolerate any “positive” input injection current from input sources > 5.5V.
- 7:** Non-zero injection currents can affect the ADC results by approximately 4-6 counts.
- 8:** Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the mathematical “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DI60a	I _{ICL}	Input Low Injection Current	0	—	-5 ^(4,7)	mA	All pins except V _{DD} , V _{SS} , AV _{DD} , AV _{SS} , MCLR, VCAP and RB7
DI60b	I _{ICH}	Input High Injection Current	0	—	+5 ^(5,6,7)	mA	All pins except V _{DD} , V _{SS} , AV _{DD} , AV _{SS} , MCLR, VCAP, RB7 and all 5V tolerant pins ⁽⁶⁾
DI60c	ΣI_{ICT}	Total Input Injection Current (sum of all I/O and control pins)	-20 ⁽⁸⁾	—	+20 ⁽⁸⁾	mA	Absolute instantaneous sum of all $\pm$ input injection currents from all I/O pins ($ I_{ICL} + I_{ICH} $) $\leq \Sigma I_{ICT}$

- Note 1:** The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.
- 2:** Negative current is defined as current sourced by the pin.
- 3:** See the “Pin Diagrams” section for the 5V tolerant I/O pins.
- 4:** V_{IL} source < (V_{SS} – 0.3). Characterized but not tested.
- 5:** Non-5V tolerant pins V_{IH} source > (V_{DD} + 0.3), 5V tolerant pins V_{IH} source > 5.5V. Characterized but not tested.
- 6:** Digital 5V tolerant pins cannot tolerate any “positive” input injection current from input sources > 5.5V.
- 7:** Non-zero injection currents can affect the ADC results by approximately 4-6 counts.
- 8:** Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the mathematical “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 30-33: SPI2 MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended		
Maximum Data Rate	Master Transmit Only (Half-Duplex)	Master Transmit/Receive (Full-Duplex)	Slave Transmit/Receive (Full-Duplex)	CKE	CKP	SMP
15 MHz	Table 30-33	—	—	0,1	0,1	0,1
9 MHz	—	Table 30-34	—	1	0,1	1
9 MHz	—	Table 30-35	—	0	0,1	1
15 MHz	—	—	Table 30-36	1	0	0
11 MHz	—	—	Table 30-37	1	1	0
15 MHz	—	—	Table 30-38	0	1	0
11 MHz	—	—	Table 30-39	0	0	0

FIGURE 30-14: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0)
TIMING CHARACTERISTICS

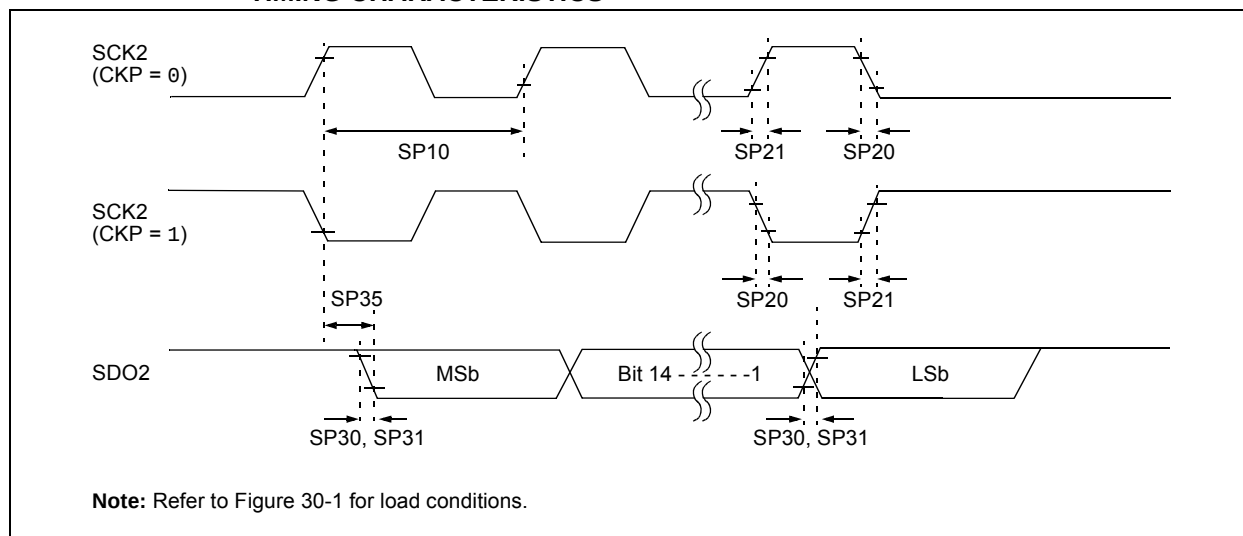


FIGURE 30-37: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS
(CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000, SSRG = 0)

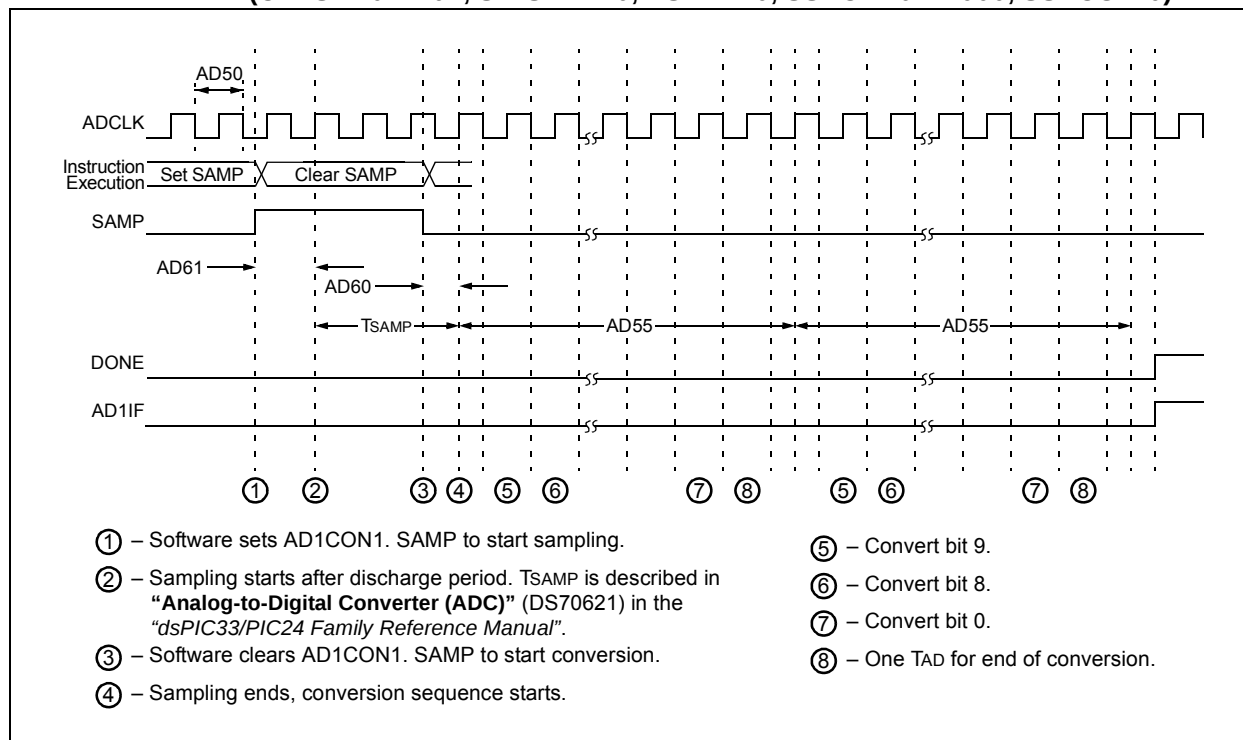
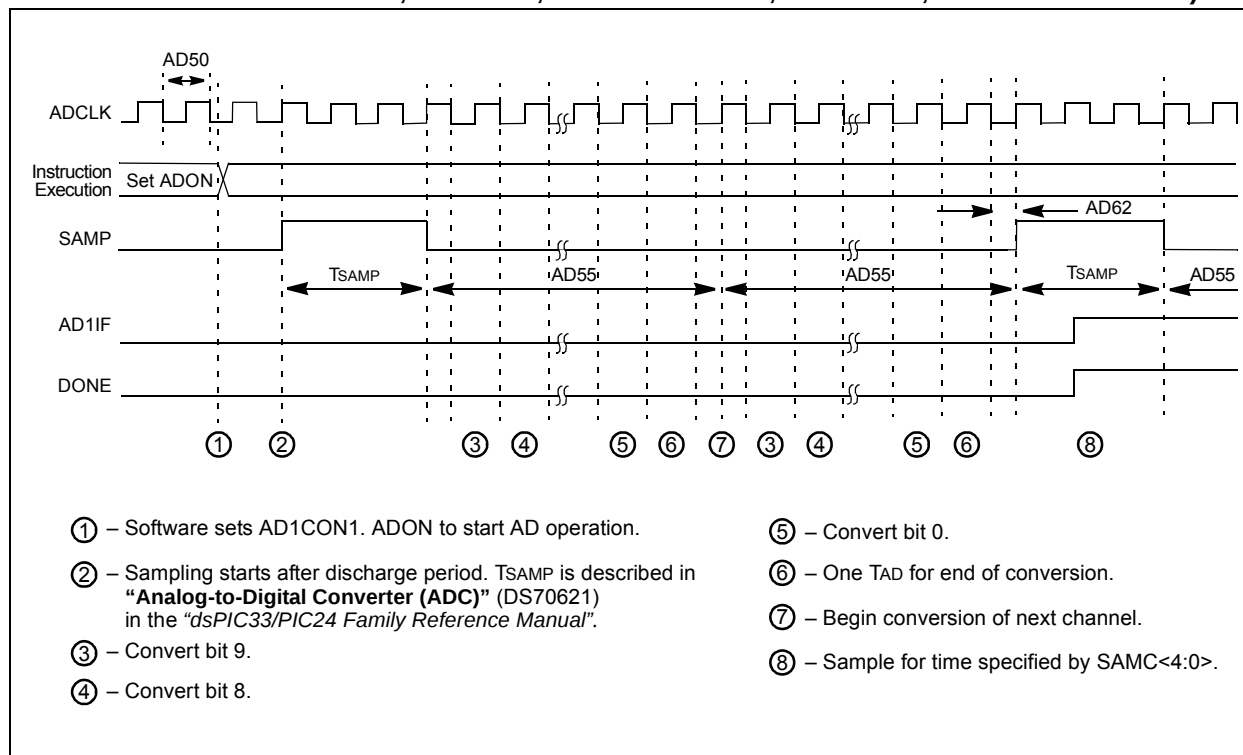
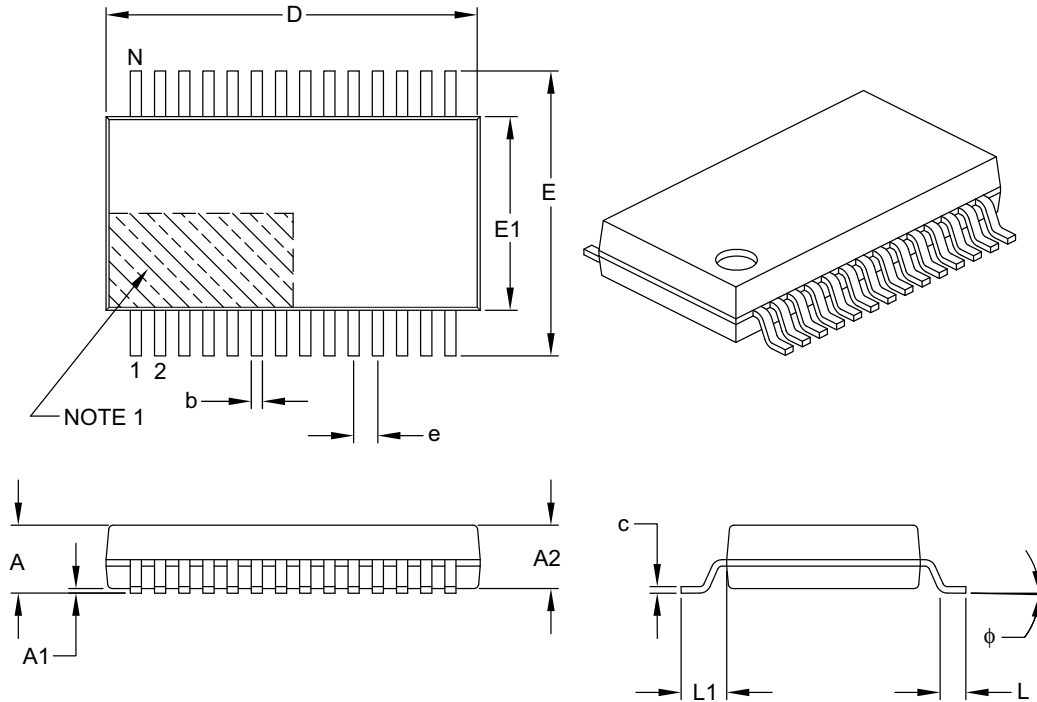


FIGURE 30-38: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SSRG = 0, SAMC<4:0> = 00010)



28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1	1.25 REF		
Lead Thickness	c	0.09	–	0.25
Foot Angle	φ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

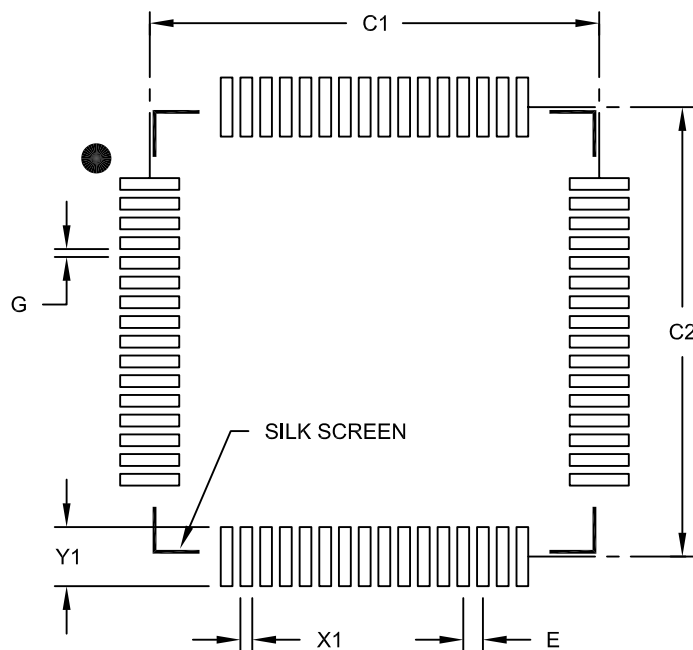
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

64-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085B

APPENDIX A: REVISION HISTORY

Revision A (April 2011)

This is the initial released version of the document.

Revision B (July 2011)

This revision includes minor typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in Table A-1.

TABLE A-1: MAJOR SECTION UPDATES

Section Name	Update Description
“High-Performance, 16-bit Digital Signal Controllers and Microcontrollers”	Changed all pin diagrams references of VLAP to TLA.
Section 4.0 “Memory Organization”	Updated the All Resets values for CLKDIV and PLLFBD in the System Control Register Map (see Table 4-35).
Section 5.0 “Flash Program Memory”	Updated “one word” to “two words” in the first paragraph of Section 5.2 “RTSP Operation” .
Section 9.0 “Oscillator Configuration”	Updated the PLL Block Diagram (see Figure 9-2). Updated the Oscillator Mode, Fast RC Oscillator (FRC) with divide-by-N and PLL (FRCPLL), by changing (FRCDIVN + PLL) to (FRCPLL). Changed (FRCDIVN + PLL) to (FRCPLL) for COSC<2:0> = 001 and NOSC<2:0> = 001 in the Oscillator Control Register (see Register 9-1). Changed the POR value from 0 to 1 for the DOZE<1:0> bits, from 1 to 0 for the FRCDIV<0> bit, and from 0 to 1 for the PLLPOST<0> bit; Updated the default definitions for the DOZE<2:0> and FRCDIV<2:0> bits and updated all bit definitions for the PLLPOST<1:0> bits in the Clock Divisor Register (see Register 9-2). Changed the POR value from 0 to 1 for the PLLDIV<5:4> bits and updated the default definitions for all PLLDIV<8:0> bits in the PLL Feedback Division Register (see Register 9-2).
Section 22.0 “Charge Time Measurement Unit (CTMU)”	Updated the bit definitions for the IRNG<1:0> bits in the CTMU Current Control Register (see Register 22-3).
Section 25.0 “Op amp/ Comparator Module”	Updated the voltage reference block diagrams (see Figure 25-1 and Figure 25-2).

Revision F (November 2012)

Removed “Preliminary” from data sheet footer.

Revision G (March 2013)

This revision includes the following global changes:

- changes “ $\overline{\text{FLT}}\text{x}$ ” pin function to “FLT x ” on all occurrences
- adds **Section 31.0 “High-Temperature Electrical Characteristics”** for high-temperature (+150°C) data

This revision also includes minor typographical and formatting changes throughout the text.

Other major changes are referenced by their respective section in Table A-5.

TABLE A-5: MAJOR SECTION UPDATES

Section Name	Update Description
Cover Section	• Changes internal oscillator specification to 1.0% • Changes I/O sink/source values to 12 mA or 6 mA • Corrects 44-pin VTLA pin diagram (pin 32 now shows as 5V tolerant)
Section 4.0 “Memory Organization”	• Deletes references to Configuration Shadow registers • Corrects the spelling of the JTAGIP and PTGWD$\overline{\text{TIP}}$ bits throughout • Corrects the Reset value of all IOCON registers as C000h • Adds footnote to Table 4-42 to indicate the absence of Comparator 3 in 28-pin devices
Section 6.0 “Resets”	• Removes references to cold and warm Resets, and clarifies the initial configuration of the device clock source on all Resets
Section 7.0 “Interrupt Controller”	• Corrects the definition of GIE as “Global Interrupt Enable” (not “General”)
Section 9.0 “Oscillator Configuration”	• Clarifies the behavior of the CF bit when cleared in software • Removes POR behavior footnotes from all control registers • Corrects the tuning range of the TUN<5:0> bits in Register 9-4 to an overall range $\pm 1.5\%$
Section 13.0 “Timer2/3 and Timer4/5”	• Clarifies the presence of the ADC Trigger in 16-bit Timer3 and Timer5, as well as the 32-bit timers
Section 15.0 “Output Compare”	• Corrects the first trigger source for SYNCSEL<4:0> (OCxCON2<4:0>) as OCxRS match
Section 16.0 “High-Speed PWM Module”	• Clarifies the source of the PWM interrupts in Figure 16-1 • Corrects the Reset states of IOCONx<15:14> in Register 16-13 as ‘11’
Section 17.0 “Quadrature Encoder Interface (QEI) Module”	• Clarifies the operation of the IMV<1:0> bits (QEICON<9:8>) with updated text and additional notes • Corrects the first prescaler value for QFVDIV<2:0> (QE1IOC<13:11>), now 1:128
Section 23.0 “10-Bit/12-Bit Analog-to-Digital Converter (ADC)”	• Adds note to Figure 23-1 that Op Amp 3 is not available in 28-pin devices • Changes “sample clock” to “sample trigger” in AD1CON1 (Register 23-1) • Clarifies footnotes on op amp usage in Registers 23-5 and 23-6
Section 25.0 “Op Amp/Comparator Module”	• Adds Note text to indicate that Comparator 3 is unavailable in 28-pin devices • Splits Figure 25-1 into two figures for clearer presentation (Figure 25-1 for Op amp/Comparators 1 through 3, Figure 25-2 for Comparator 4). Subsequent figures are renumbered accordingly. • Corrects reference description in xxxxx (now (AVDD+AVSS)/2) • Changes CMSTAT<15> in Register 25-1 to “PSIDL”
Section 27.0 “Special Features”	• Corrects the addresses of all Configuration bytes for 512 Kbyte devices